

REV	MODIFICATION	DATE	DRAW
D	EN-13-1105	2013.11.14	EvanTeng
E	ECN2-0000019	2013.12.03	EvanTeng
F	ECN2-00000181	2014.12.02	Stacy

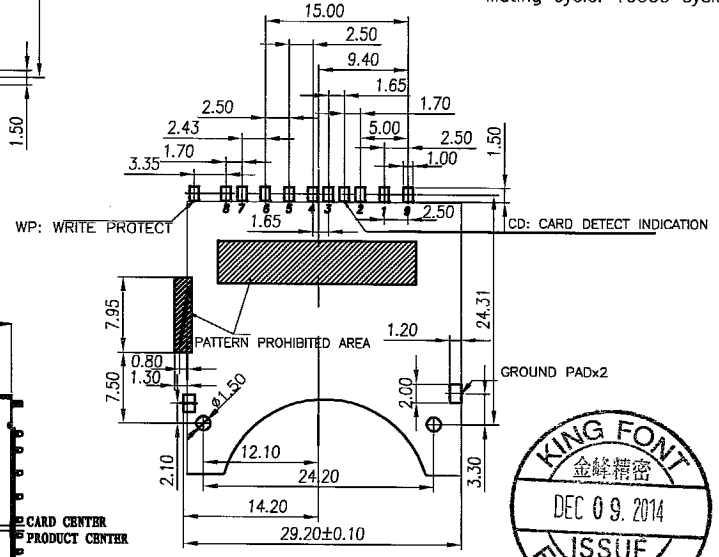
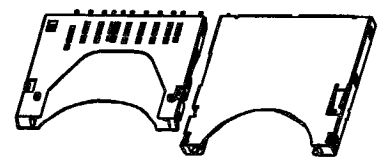
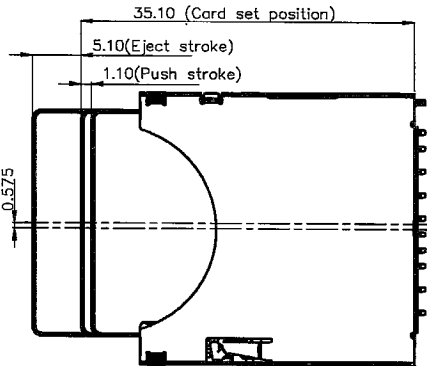
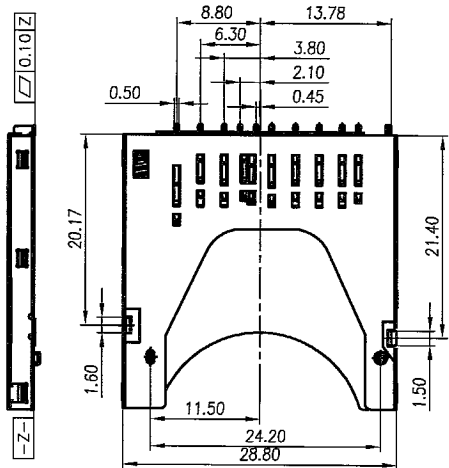
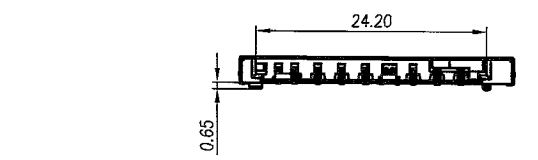
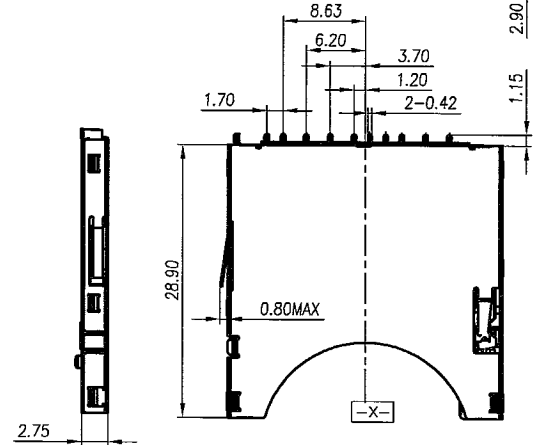
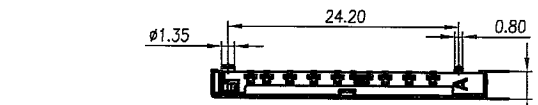
SPECIFICATION

1. Material:

Insulator: LCP, rated UL94V-0,color:black.
 Contacts; Phosphor Bronze,
 Tin 160u" at Solder Tail,
 Selected Gold on Contact Area Plating.
 Ground:Phosphor Bronze,Tin 160u".
 Shell: Stainless.

2. Electrical Characteristics:

Operating voltage : 50V(AC/DC).
 Current rating : 0.5 A.
 Operating Temperature: -25°C~+90°C.
 Insulation resistance: 1000M ohms min. at 500VDC
 Dielectric withstanding voltage:500 VAC/1minute.
 Contact resistance: 100m ohms max.
 Mating cycle: 10000 cycles, spring is not breaking..



Pin No.	SD	MMC
P1	MMC-DAT3 SD-CD/DAT3	1P 1P
P2	MMC-CMD SD-CMD	2P 2P
P3	MMC-VSS1 SD-VSS1	3P 3P
P4	MMC-VDD SD-VDD	4P 4P
P5	MMC-CLK SD-CLK	5P 5P
P6	MMC-VSS2 SD-VSS2	6P 6P
P7	MMC-DAT0 SD-DAT0	7P 7F
P8	SD-DAT1	8P
P9	SD-DAT2	9P

CIRCUIT:	WP	GROUND	WP	GROUND	WP	GROUND
WITHOUT CARD	○	○	○	○	○	○
	○	#3	○	#3	○	#3
CARD INSERTED	○	○	○	○	○	○
WRITE PROTECT : LOCK	○	○	○	○	○	○
CARD INSERTED	○	○	○	○	○	○
WRITE PROTECT : UNLOCK	○	○	○	○	○	○

Ordering Information:

SDDMF-0 T 9 XX B X 04-G

PLATING TYPE _____
 T : COMPLY TO RoHS
 Contact Area Plating: _____
 0 : TRAY
 1 : TAPE REEL

- 01 : G/F Plating
- 03 : 3u" Gold Plating
- 05 : 5u" Gold Plating
- 10 : 10u" Gold Plating
- 15 : 15u" Gold Plating
- 30 : 30u" Gold Plating

RECOMMENDED PCB LAYOUT
 (ALL TOLERANCE ARE ±0.05)



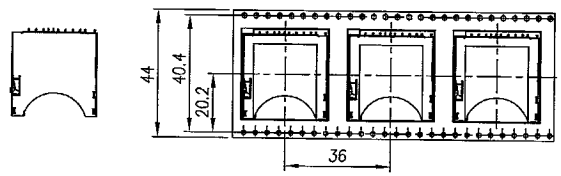
DIMENSION IN mm [Inch]	PROD. SPEC. SP0890	KINGFONT PRECISION INDUSTRIAL CO., LTD.	
TOLERANCE UNLESS OTHERWISE SPECIFIED	PKG. SPEC. 3/3	TITLE SD MEMORY CARD PUSH-PUSH CONNECTOR TYPE	CUSTOMER DRAWING
.X±0.30 X.*±10'	APPROVE <i>Cam</i>	FILE NO.	DWG NO. SDDMF-0T9XXBX04-G
.XX±0.20 .X.*±5'	CHECK <i>Jay</i>	SIZE A4	PROJ. SHEET 1/3
.XXX±0.05 .XX.*±1'	DRAW <i>3/3</i>	SCALE 1.5:1	REV F

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E	ECN2-00000019	2013.12.03	EvanTeng
F	ECN2-00000181	2014.12.02	Stacy

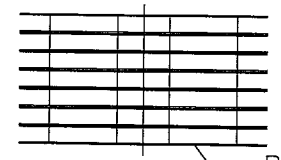
包裝作業規範

包裝作業圖示及說明 (PACKING OPERATION DIAGRAM & INSTRUCTION)

- 一、
- (1) 將成品一一放入REEL包裝盤內, 依同依方向放入
 - (2) 包裝時, 如圖所示
 - (3) 一個REEL包裝盤放置450個成品

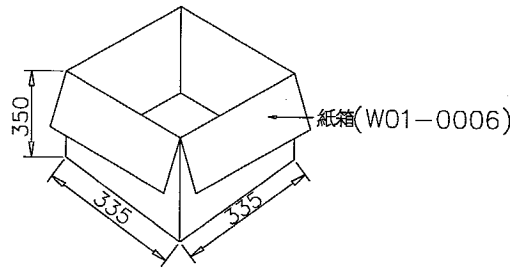
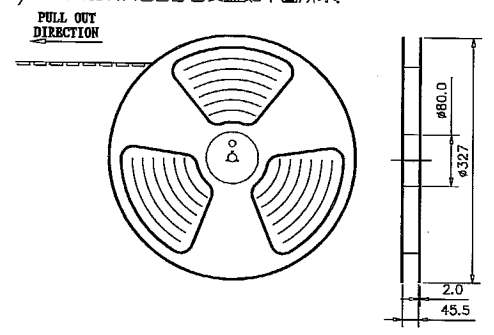


- 三、
- (1) 每箱裝6盤REEL包裝盤
 - (2) 每箱放置2700PCS的成品



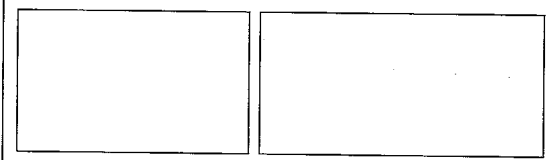
REEL盤(W06-0009)

- 二、
- (1) 裝盤前把前面空10PCS產品, 然後再開始裝盤, 尾端也需空10CS產品.
 - (2) 裝滿成品的REEL包裝盤如下圖所示



紙箱(W01-0006)

- 四、
- (1) 用TPAE將紙箱封實



備註 (REMARK)

1. 若有未裝滿之零數箱, 必須以緩衝材塞滿.



DIMENSION IN mm [Inch]		PROD. SPEC. SP0890	KINGFONT KINGFONT PRECISION INDUSTRIAL CO., LTD.	
TOLERANCE UNLESS OTHERWISE SPECIFIED		PKG. SPEC. 2/3/3	TITLE SD MEMORY CARD PUSH-PUSH CONNECTOR TYPE	CUSTOMER DRAWING
.X± 0.30	X."± 10"	APPROVE Gary	FILE NO.	DWG NO. SDDMF-0T9XXBX04-G
.XX± 0.20	.X"± 5"	CHECK Joey	SIZE A4	PROJ. SHEET 2 / 3
.XXX± 0.05	.XX"± 1"	DRAW 30	SCALE 1.5:1	REV F

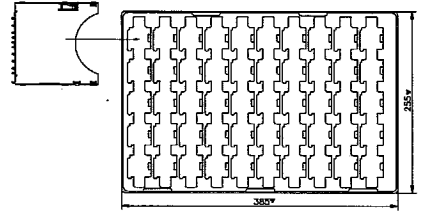
1 | 2 | 3 | 4 | 5 | 6 | 7 | 8

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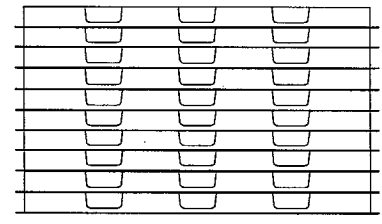
包裝作業規範

包裝作業圖示及說明 (PACKING OPERATION DIAGRAM & INSTRUCTION)

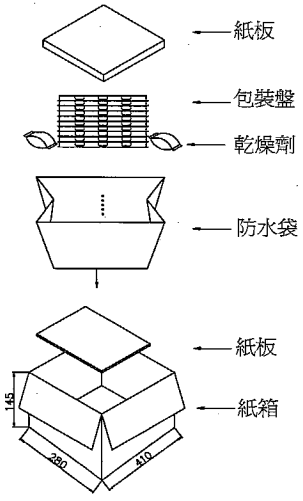
- 一、
- (1) 將成品一一放入包裝盤內,依同一方向放入。
 - (2) 包裝時,如圖所示
 - (3) 一個包裝盤放置50個成品



- 二、
- (1) 將放滿成品的包裝盤依同一方向一層層疊好。
 - (2) 如圖所示



- 三、
- (1) 每箱需放置21個包裝盤
 - (2) 最後面一個包裝盤作為上蓋,固不放置成品。
 - (3) 每箱放置1000 PCS的成品。
 - (4) 將成品放置塑膠袋內,上下面各放一包乾燥劑,包裝完成後再裝箱。



- 四、
- (1) 用TAPE將紙箱封實。

	C/NO: MADE IN CHINA
ITEM NO: QTY.: G.W.: N.W.: MEAS:	PCS KGS KGS cm

備註 (REMARK)

1. 若有未裝滿之零數箱,必須以緩衝材塞滿。



DIMENSION IN mm [Inch]		PROD. SPEC. SP0890	KINGFONT PRECISION INDUSTRIAL CO., LTD.	
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.X±0.30	.X"±10"	APPROVE <i>Comy</i>	FILE NO.	DWG NO. SDDMF-0T9XXBX04-G
.XX±0.20	.X"±5"	CHECK <i>Stacy</i>	SIZE A4	PROJ. SHEET 3 / 3
.XXX±0.05	.XX"±1"	DRAW <i>Stacy</i>	SCALE 1.5:1	REV F

1 | 2 | 3 | 4 | 5 | 6 | 7 | 8 QR-2100-043